INTEGRATED CIRCUITS

DATA SHEET

74ALVCH162827

20-bit buffer/line driver, non-inverting, with 30Ω termination resistors (3-State)

Product specification

1998 Sep 29

IC24 Data Handbook





20-bit buffer/line driver, non-inverting, with 30 Ω termination resistors (3-State)

74ALVCH162827

FEATURES

- Complies with JEDEC standard no. 8-1A.
- CMOS low power consumption
- Direct interface with TTL levels
- Current drive ± 12 mA at 3.0 V
- MULTIBYTETM flow-through standard pin-out architecture
- Low inductance multiple V_{CC} and GND pins for minimum noise and ground bounce
- Integrated 30 Ω termination resistors

DESCRIPTION

The 74ALVCH162827 high-performance CMOS device combines low static and dynamic power dissipation with high speed and high output drive.

The 74ALVCH162827 20-bit buffers provide high performance bus interface buffering for wide data/address paths or buses carrying parity. They have NAND Output Enables (nOE1, nOE2) for maximum control flexibility.

The 74ALVCH162827 is designed with 30Ω series resistance in both the pull-up and pull-down output structures. This design reduces line noise in applications such as memory address drivers, clock drivers and bus receivers/transmitters.

To ensure the high impedance state during power up or power down, \overline{OE} should be tied to V_{CC} through a pullup resistor; the minimum value of the resistor is determined by the current-sinking/current-sourcing capability of the driver.

Active bus-hold circuitry is provided to hold unused or floating data inputs at a valid logic level.

QUICK REFERENCE DATA

GND = 0V; $T_{amb} = 25^{\circ}C$; $t_r = t_f = 2.5$ ns

SYMBOL	PARAMETER	CONDITION	TYPICAL	UNIT		
t _{PHL} /t _{PLH}	Propagation delay nAn to nYn	$V_{CC} = 2.5V, C_L = 30pF$ $V_{CC} = 3.3V, C_L = 50pF$		2.9 2.9	ns	
C _I	Input capacitance			5	pF	
Con	Power dissipation capacitance per latch	$V_1 = GND \text{ to } V_{CC}^1$	Output enabled	14	pF	
C _{PD}	l ower dissipation capacitance per laten	VI = GIAD to AGG	Output disabled	3] "	

NOTES:

 C_{PD} is used to determine the dynamic power dissipation (PD in $\mu W)$:

 $P_D = C_{PD} \times V_{CC}^2 \times f_i + \Sigma (C_L \times V_{CC}^2 \times f_o)$ where: $P_D = C_{PD} \times V_{CC}^2 \times f_o$ in MHz; $P_D = C_{PD} \times V_{CC}^2 \times f_o$ where: $P_D = C_D \times V_{CC}^2 \times f_o$

 $\Sigma (C_L \times V_{CC}^2 \times f_0) = \text{sum of outputs.}$

ORDERING INFORMATION

PACKAGES	TEMPERATURE RANGE	OUTSIDE NORTH AMERICA	NORTH AMERICA	DWG NUMBER
56-Pin Plastic TSSOP Type II	–40°C to +85°C	74ALVCH162827DGG	ACH162827DGG	SOT364-1

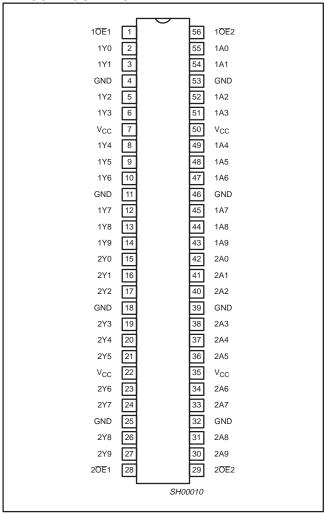
PIN DESCRIPTION

PIN NUMBER	SYMBOL	FUNCTION
55, 54, 52, 51, 49, 48, 47, 45, 44, 43, 42, 41, 40, 38, 37, 36, 34, 33, 31, 30	1A0 - 1A9 2A0 - 2A9	Data inputs
2, 3, 5, 6, 8, 9, 10, 12, 13, 14, 15, 16, 17, 19, 20, 21, 23, 24, 26, 27	1Y0 - 1Y9 2Y0 - 2Y9	Data outputs
1, 56, 28, 29	1 <u>0E</u> 1 1 <u>0E</u> 2, 2 <u>0E</u> 1, 2 <u>0E</u> 2	Output enable inputs (active-LOW)
4, 11, 18, 25, 32, 39, 46, 53	GND	Ground (0V)
7, 22, 35, 50	V _{CC}	Positive supply voltage

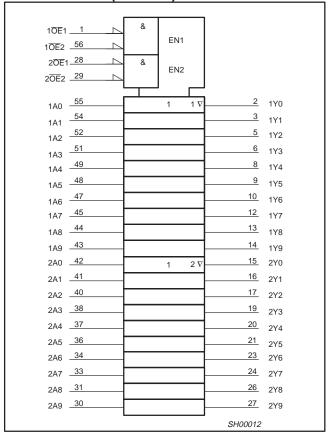
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74ALVCH162827

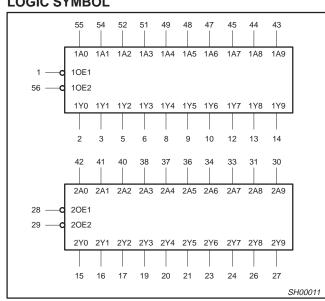
PIN CONFIGURATION



LOGIC SYMBOL (IEEE/IEC)



LOGIC SYMBOL



FUNCTION TABLE

	INPUTS		OUTPUT	OPERATING MODE
nOE1	nOE2	nAn	nYn	OF ERATING WIDDE
L	L	L	L	Transparent
L	L	Н	Н	Transparent
Н	Х	Х	Z	High impedance
Х	Н	Х	Z	High impedance

X = Don't care

Z = High impedance "off" state

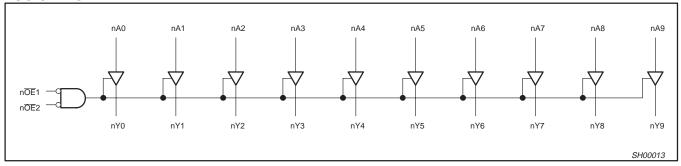
H = High voltage level

L = Low voltage level

20-bit buffer/line driver, non-inverting, with 30Ω termination resistors (3-State)

74ALVCH162827

LOGIC DIAGRAM



RECOMMENDED OPERATING CONDITIONS

SYMBOL	PARAMETER	CONDITIONS	MIN	MAX	UNIT
V	DC supply voltage 2.5V range (for max. speed performance @ 30 pF output load)		2.3	2.7	V
Vcc	DC supply voltage 3.3V range (for max. speed performance @ 50 pF output load)		3.0	3.6	V
VI	DC Input voltage range		0	V _{CC}	V
V _O	DC output voltage range		0	V _{CC}	V
T _{amb}	Operating free-air temperature range		-40	+85	°C
t _r , t _f	Input rise and fall times	$V_{CC} = 2.3 \text{ to } 3.0 \text{V}$ $V_{CC} = 3.0 \text{ to } 3.6 \text{V}$	0 0	20 10	ns/V

ABSOLUTE MAXIMUM RATINGS

In accordance with the Absolute Maximum Rating System (IEC 134) Voltages are referenced to GND (ground = 0V)

SYMBOL	PARAMETER	CONDITIONS	RATING	UNIT	
V _{CC}	DC supply voltage		-0.5 to +4.6	V	
I _{IK}	DC input diode current	V _I < 0	-50	mA	
VI	DC input voltage	Note 1	-0.5 to +4.6	V	
I _{OK}	DC output diode current	$V_O > V_{CC}$ or $V_O < 0$	±50	mA	
Vo	DC output voltage	Note 1	-0.5 to V _{CC} +0.5	V	
I _O	DC output source or sink current	$V_O = 0$ to V_{CC}	±50	mA	
I _{GND} , I _{CC}	DC V _{CC} or GND current		±100	mA	
T _{stg}	Storage temperature range		-65 to +150	°C	
P _{TOT}	Power dissipation per package –plastic thin-medium-shrink (TSSOP)	For temperature range: –40 to +125 °C above +55°C derate linearly with 8 mW/K	600	600 mW	

NOTE:

^{1.} The input and output voltage ratings may be exceeded if the input and output current ratings are observed.

20-bit buffer/line driver, non-inverting, with $30\boldsymbol{\Omega}$ termination resistors (3-State)

74ALVCH162827

DC ELECTRICAL CHARACTERISTICS

Over recommended operating conditions. Voltage are referenced to GND (ground = 0 V).

				LIMITS			
SYMBOL	PARAMETER	TEST CONDITIONS	Temp =	= -40°C to +8	5°C	UNIT	
			MIN	TYP ¹	MAX	1	
.,		V _{CC} = 2.3 to 2.7V	1.7	1.2		,,	
V_{IH}	HIGH level Input voltage	V _{CC} = 2.7 to 3.6V	2.0	1.5		V	
	$V_{CC} = 2.3 \text{ to } 2.7 \text{V}$			1.2	0.7	.,	
V_{IL}	LOW level Input voltage	V _{CC} = 2.7 to 3.6V		1.5	0.8	\ \	
		V_{CC} = 2.3 to 3.6V; V_I = V_{IH} or V_{IL} ; I_O = $-100\mu A$	V _{CC} -0.2	V _{CC}			
		$V_{CC} = 2.3V$; $V_I = V_{IH}$ or V_{IL} ; $I_O = -4mA$	V _{CC} -0.4	V _{CC} -0.11		1	
		$V_{CC} = 2.3V$; $V_I = V_{IH}$ or V_{IL} ; $I_O = -6mA$	V _{CC} -0.6	V _{CC} -0.17		1	
V_{OH}	HIGH level output voltage	$V_{CC} = 2.7V$; $V_I = V_{IH}$ or V_{IL} ; $I_O = -4mA$	V _{CC} -0.5	V _{CC} -0.09		V	
		$V_{CC} = 2.7V$; $V_I = V_{IH}$ or V_{IL} ; $I_O = -8mA$	V _{CC} -0.7	V _{CC} -0.19		1	
		$V_{CC} = 3.0V$; $V_I = V_{IH}$ or V_{IL} ; $I_O = -6mA$	V _{CC} -0.6	V _{CC} -0.13		1	
		$V_{CC} = 3.0V$; $V_I = V_{IH}$ or V_{IL} ; $I_O = -12mA$	V _{CC} -1.0	V _{CC} -0.27		1	
		V_{CC} = 2.3 to 3.6V; V_I = V_{IH} or V_{IL} ; I_O = 100 μ A		GND	0.20		
		$V_{CC} = 2.3V$; $V_I = V_{IH}$ or V_{IL} ; $I_O = 4mA$		0.07	0.40	1	
		$V_{CC} = 2.3V$; $V_I = V_{IH}$ or V_{IL} ; $I_O = 6mA$		0.11	0.55	1	
V_{OL}	LOW level output voltage	$V_{CC} = 2.7V$; $V_I = V_{IH}$ or V_{IL} ; $I_O = 4mA$		0.06	0.40	٧	
		$V_{CC} = 2.7V$; $V_I = V_{IH}$ or V_{IL} ; $I_O = 8mA$		0.13	0.60]	
		$V_{CC} = 3.0V$; $V_I = V_{IH}$ or V_{IL} ; $I_O = 6mA$		0.09	0.55		
		$V_{CC} = 3.0V$; $V_I = V_{IH}$ or V_{IL} ; $I_O = 12mA$		0.19	0.80	1	
IĮ	Input leakage current	V_{CC} = 2.3 to 3.6V; V_I = V_{CC} or GND		0.1	5	μА	
I _{OZ}	3-State output OFF-state current	V_{CC} = 2.3 to 3.6V; V_I = V_{IH} or V_{IL} ; V_O = V_{CC} or GND		0.1	10	μА	
I _{CC}	Quiescent supply current	$V_{CC} = 2.3$ to 3.6V; $V_I = V_{CC}$ or GND; $I_O = 0$		0.2	40	μΑ	
ΔI_{CC}	Additional quiescent supply current	$V_{CC} = 2.3V \text{ to } 3.6V; V_I = V_{CC} - 0.6V; I_O = 0$		150	750	μА	
I _{BHL}	Bus hold LOW sustaining current	$V_{CC} = 2.3V; V_I = 0.7V^2$	45	-		μΑ	
la	Rue hold HIGH custoining current	$V_{CC} = 2.3V; V_I = 1.7V^2$	-45			,,,	
Iвнн	Bus hold HIGH sustaining current	$V_{CC} = 3.0V; V_1 = 2.0V^2$	- 75	-175		μА	
I _{BHLO}	Bus hold LOW overdrive current	$V_{CC} = 3.6V^2$	500			μΑ	
I _{BHHO}	Bus hold HIGH overdrive current	$V_{CC} = 3.6V^2$	-500			μΑ	

5

All typical values are at T_{amb} = 25°C.
Valid for data inputs of bus hold parts.

20-bit buffer/line driver, non-inverting, with $30 \ensuremath{\Omega}$ termination resistors (3-State)

74ALVCH162827

AC CHARACTERISTICS FOR V_{CC} = 2.5V \pm 0.2V

 $GND = 0V; \ t_r = t_f \leq 2.0ns; \ C_L = 30pF$

	SYMBOL PARAMETER					
SYMBOL			V	UNIT		
			MIN	TYP ¹	MAX	
t _{PHL} /t _{PLH}	Propagation delay nAn to nYn	1, 3	1.0	2.9	4.6	ns
t _{PZH} /t _{PZL}	3-State output enable time nOEn to nYn	2, 3	1.4	3.9	6.4	ns
t _{PHZ} /t _{PLZ}	3-State output disable time nOEn to nYn	2,3	1.7	2.2	5.9	ns

NOTE:

AC CHARACTERISTICS FOR V_{CC} = 3.0V \pm 0.3V

 $GND = 0V; \ t_r = t_f \le 2.5 ns; \ C_L = 50 pF$

	SYMBOL PARAMETER			LIMITS		LIM		
SYMBOL			YMBOL PARAMETER WAVEFORM		٧c	$_{\rm CC}$ = 3.3 \pm 0.3	3V	V _{CC} =
			MIN	TYP ^{1, 2}	MAX	TYP ¹	MAX	
t _{PHL} /t _{PLH}	Propagation delay nAn to nYn	1, 3	1.5	2.9	4.2	3.1	4.7	ns
t _{PZH} /t _{PZL}	3-State output enable time nOEn to nYn	2, 3	1.6	3.7	5.4	4.4	6.5	ns
t _{PHZ} /t _{PLZ}	3-State output disable time nOEn to nYn	2, 3	1.8	3.0	4.7	3.2	5.2	ns

- 1. All typical values are at V_{CC} T_{amb} = 25°C. 2. Typical value is measured at V_{CC} = 3.3V.

^{1.} All typical values are at V_{CC} = 2.5V and T_{amb} = 25°C.

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74ALVCH162827

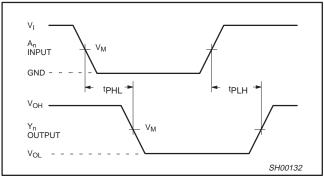
AC WAVEFORMS FOR $V_{CC} = 2.3V$ TO 2.7V

 $V_{M} = 0.5 V_{CC}$ $V_{X} = V_{OL} + 0.15 V_{CC}$ $V_Y = V_{OH} - 0.15V$ V_{OL} and V_{OH} are the typical output voltage drop that occur with the output load.

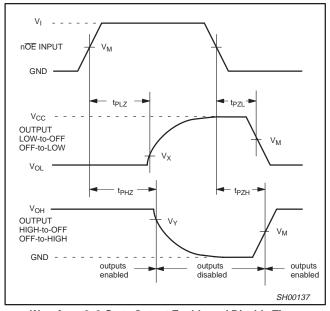
AC WAVEFORMS FOR $V_{CC} = 3.0V$ TO 3.6V AND $V_{CC} = 2.7V RANGE$

 $V_{M} = 1.5 \text{ V}$ $V_{X} = V_{OL} + 0.3 \text{V}$

 $V_Y = V_{OH} - 0.3V$ V_{OL} and V_{OH} are the typical output voltage drop that occur with the output load.

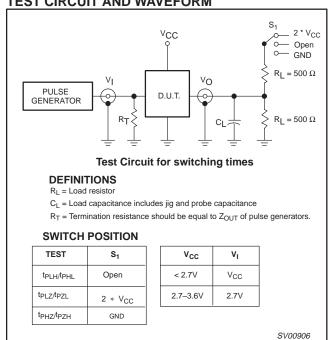


Waveform 1. Input (nAx) to Output (nYx) Propagation Delays



Waveform 2. 3-State Output Enable and Disable Times

TEST CIRCUIT AND WAVEFORM

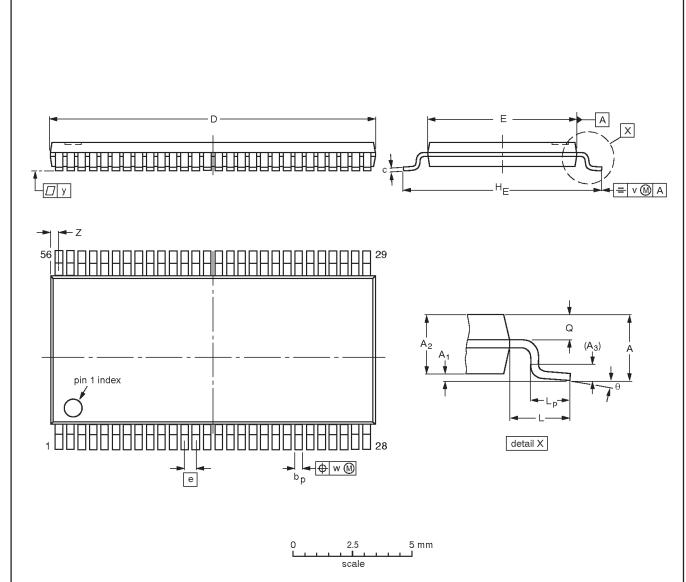


Waveform 3. Load circuitry for switching times

20-bit buffer/line driver, non-inverting, with 30Ω termination resistors (3-State)

TSSOP56: plastic thin shrink small outline package; 56 leads; body width 6.1mm

SOT364-1



DIMENSIONS (mm are the original dimensions).

UNIT	A max.	A ₁	A ₂	А3	bp	С	D ⁽¹⁾	E ⁽²⁾	е	HE	L	Lp	Q	٧	w	у	z	θ
mm	1.2	0.15 0.05	1.05 0.85	0.25	0.28 0.17	0.2 0.1	14.1 13.9	6.2 6.0	0.5	8.3 7.9	1.0	0.8 0.4	0.50 0.35	0.25	0.08	0.1	0.5 0.1	8° 0°

Notes

- 1. Plastic or metal protrusions of 0.15 mm maximum per side are not included.
- 2. Plastic interlead protrusions of 0.25 mm maximum per side are not included.

OUTLINE		REFER	EUROPEAN	ISSUE DATE		
VERSION	IEC	JEDEC	EIAJ		PROJECTION	1330E DATE
SOT364-1		MO-153EE				-93-02-03 95-02-10

1998 Sep 29 8

20-bit buffer/line driver, non-inverting, with 30Ω termination resistors (3-State)

74ALVCH162827

NOTES

1998 Sep 29

9

20-bit buffer/line driver, non-inverting, with 30Ω termination resistors (3-State)

74ALVCH162827

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